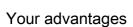


1156945

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SMD pin header, nominal current: 3 A, test voltage: 500 V AC, number of positions: 80, pitch: 2. 54 mm, color: black, contact surface: Au, contact connection type: Pin, mounting: SMD soldering



- · Reliable mechanical and electrical connections thanks to the double-sided contact system
- · Designed for integration into the SMT soldering process
- · Clear and cost-optimized design
- · Suitable for a multitude of applications

· Stacked, coplanar or orthogonal PCB connections enable maximum flexibility in the device

Commercial data

Item number	1156945
Packing unit	50 pc
Minimum order quantity	50 pc
Sales key	AA24
Product key	AAXGBA
GTIN	4063151159191
Weight per piece (including packing)	8.956 g
Weight per piece (excluding packing)	8.956 g
Customs tariff number	85366930
Country of origin	CN



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Technical data

Notes

Notes on operation	The permissible voltage during operation depends on the
	application, taking into consideration the air clearances and creepage distances within the scope of insulation requirements in
	accordance with IEC 60664-1.

Product properties

Product type	SMD pin header
Product family	FQ 2,54D/PH
Number of positions	80
Pitch	2.54 mm
Number of rows	2
Pin layout	Linear pad geometry

Electrical properties

Nominal current I _N	3 A (at 20°C 80-pos.)
Contact resistance	20 mΩ
Test voltage	500 V AC IEC 60512-4-1:2003-05

Dimensions

Dimensional drawing	P, h
Pitch	2.54 mm
Width [w]	101.6 mm
Height [h]	6.28 mm
Length [I]	16.1 mm
Installed height	5.08 mm
Application	
Contact cover	0.4 mm
Wipe length	1.3 mm
PCB design	
Pad geometry	1.3 x 2.8 mm

Material specifications

Material data - contact

Note	WEEE/RoHS-compliant, free of whiskers according to IEC 60068-2-82/JEDEC JESD 201
Contact material	Cu alloy



Dimension check
Specification

Result

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Surface characteristics	Selective coating
Metal surface contact area (top layer)	Gold (Au)
Metal surface contact area (middle layer)	Nickel (Ni)
Metal surface soldering area (top layer)	Tin (Sn)
Material data - housing	
Color (Housing)	black (9005)
Insulating material	PA
Insulating material group	I
CTI according to IEC 60112	600
Flammability rating according to UL 94	V0
Connection 1	
Insulating material	PA
CTI according to IEC 60112	600
Electrical tests	
Thermal test Test group C	
Specification	IEC 60512-5-2:2002-02
Tested number of positions	80
Insulation resistance	
Specification	IEC 60512-3-1:2002-02
Insulation resistance, neighboring positions	> 1 GΩ
Air clearances and creepage distances	
Insulating material group	I
Minimum value for clearance and creepage distance	0.4 mm
Mechanical tests Insertion and withdrawal forces	
Result	Test passed
No. of cycles	100
	2.9 N
Insertion strength per pos. approx. Withdraw strength per pos. approx.	2.9 N
withuraw strength per pos. approx.	2.3 IN
Visual inspection	
Specification	IEC 60512-1-1:2002-02
Result	Test passed

IEC 60512-1-2:2002-02

Test passed



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Environmental and real-life conditions

Specification	IEC 60068-2-6:2007-12
Frequency	10 - 55 - 10 Hz
Sweep speed	1 octave/min
Amplitude	1.52 mm
Acceleration	181 m/s²
Test duration per axis	2 h
Test directions	X-, Y- and Z-axis

Durability test

Specification	IEC 60512-9-1:2010-03 (following)
Contact resistance R ₁	20 mΩ
Contact resistance R ₂	30 mΩ
Insertion/withdrawal cycles	100
Insulation resistance, neighboring positions	> 1 GΩ

Ambient conditions

Ambient temperature (operation)	-40 °C 125 °C
Ambient temperature (storage/transport)	-40 °C 70 °C
Relative humidity (storage/transport)	30 % 70 %
Ambient temperature (assembly)	-5 °C 100 °C

Mounting

Mounting type	SMD soldering
Pin layout	Linear pad geometry
Processing notes	
Process	Reflow soldering
	Reliow soldering

260 °C

Packaging specifications

Classification temperature $T_{\rm c}$

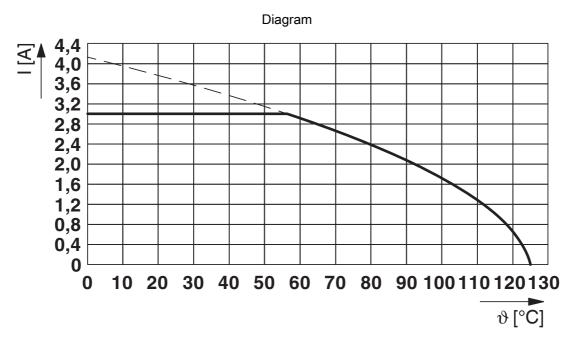
Type of packaging	Tube magazine
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Drawings



Type: FQ 2,54D/...-SH-O-BT with FQ 2,54D/...-PH-1-BT



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Approvals

To download certificates, visit the product detail page: https://www.phoenixcontact.com/us/products/1156945

e 911 us	cULus Recognized Approval ID: E118976				
		Nominal voltage $\mathbf{U}_{\mathbf{N}}$	Nominal current I _N	Cross section AWG	Cross section mm ²
		30 V	3 A	-	-



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Classifications

ECLASS

	ECLASS-11.0	27460201		
	ECLASS-13.0	27460201		
	ECLASS-12.0	27460201		
ETIM				
	ETIM 9.0	EC002637		
UNSPSC				
	UNSPSC 21.0	39121400		
	01/35/30/21.0	39121400		



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Environmental product compliance

EU RoHS

Le rione			
Fulfills EU RoHS substance requirements	Yes, No exemptions		
China RoHS			
Environment friendly use period (EFUP)	EFUP-E		
	No hazardous substances above the limits		
EU REACH SVHC			
REACH candidate substance (CAS No.)	No substance above 0.1 wt%		

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